SMA JACK, EDGE MOUNT
50 OHMS, EWR-11795 SMA-J/PCB

PRODUCT CUSTOMER DRAWING

MATERIALS AND FINISHES

BODY: BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT: BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR: PTFE

PCB PAD (FOR REFERENCE ONLY)

BOARD THICKNESS: .062 [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER ON BOTTOM (GROUND) SIDE

PS-89675-3460
PRODUCT SPECIFICATION

MIL-STD-348B, FIG. 310-2

INTERFACE

SPECIFICATION

DESCRIPTION

PART NO.

BODY
CONTACT
DESCRIPTION

PACKAGING

73251-1153
GOLD (1µ-in MIN) OVER NICKEL (50µ-in MIN)
GOLD (5µ-in MIN) OVER NICKEL (50µ-in MIN)
TRAY (80 PIECES)

73251-1152
GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)
GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)
TRAY (20 PIECES)

73251-1151
GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)
GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)
ONE 73251-1150 PER BAG

73251-1150
GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)
GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)
TRAY (80 PIECES)

MATERIALS AND FINISHES

BODY: BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT: BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR: PTFE

PCB PAD (FOR REFERENCE ONLY)

BOARD THICKNESS: .062 [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER ON BOTTOM (GROUND) SIDE